

ABSTRACT OF THE DISCLOSURE

In an apparatus and method for obtaining offset amount between a reference pattern on, for instance, a semiconductor device and a bonding tool in order to specify bonding points on the semiconductor device, a reduction process is performed on the high-magnification image acquired by a first camera, and this processed image is compared with a low-magnification image acquired by a second camera, thus obtaining an amount of deviation between an image center mark that constitutes the reference point of the high-magnification image and an image center mark that constitutes the reference point of the low-magnification image. Then, the offset amount between the second camera and the bonding tool is calculated by adding the calculated amount of deviation to the offset amount between the first camera and the bonding tool.

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